



Description

The 2N6504 is designed primarily for half-wave AC control applications, such as motor controls, heating controls and power supply crowbar circuits.

Features

- Glass Passivated Junctions for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 Volts
- 300 A Surge Current Capability
- Pb-Free Package is Available

Additional Information







Accessories

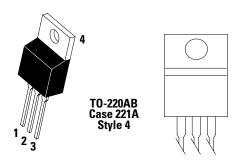


Samples

Functional Diagram



Pin Out





Maximum Ratings $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

Rating		Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (Gate Open, Sine Wave 50 to 60 Hz, $T_J = 25$ to 125°C)	2N6504 2N6505 2N6507 2N6508 2N6509	V _{DRM} ,	50 100 400 600 800	V
On-State RMS Current (180° Conduction Angles; T _C = 85°C)	I _{T (RMS)}	25	А
Average On-State Current (180° Conduction Angles; T _c = 85°C)		I _{T (AV)}	16	А
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T ₁ = 100°C)		I _{TSM}	250	А
Forward Peak Gate Power (Pulse Width ≤ 1.0 µs, T _C = 85°C)		P_{GM}	20	W
Forward Average Gate Power (t = 8.3 ms, T_c = 85°C)		$P_{G(AV)}$	0.5	W
Forward Peak Gate Current (Pulse Width \leq 1.0 μ s, $T_{\rm C}$ = 85°C)		I _{GM}	2.0	А
Operating Junction Temperature Range		T_{J}	-40 to +125	°C
Storage Temperature Range		T _{stg}	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the

Thermal Characteristics

Rating	Symbol	Value	Unit
*Thermal Resistance, Junction to Case	R _{euc}	1.5	°C/W
*Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T _L	260	°C

^{*} Indicates JEDEC Registered Data.

Electrical Characteristics - OFF $(T_C = 25^{\circ}C \text{ unless otherwise noted})$

Characteristic		Symbol	Min	Тур	Max	Unit
†Peak Repetitive Blocking Current	T ₁ = 25°C	I _{DRM} ,	-	-	10	μΑ
$(V_{AK} = V_{DRM} = V_{RRM}; Gate Open)$	T _J = 125°C	IRRM	-	-	2.0	mA

Electrical Characteristics - ON $(T_c = 25^{\circ}C \text{ unless otherwise noted; Electricals apply in both directions)$

Characteristic		Symbol	Min	Тур	Max	Unit	
* Forward On-State Voltage (Note 2) (ITM = 50 A)		V _{TM}	_	-	1.8	V	
* Gate Trigger Current (Continuous dc)		T _C = 25°C		-	9.0	30	mΛ
$(V_{AK} = 12 V_{dc'} RL = 100)$		$T_{\rm c}^{\rm C} = -40^{\circ}{\rm C}$		_	_	75	mA
* Gate Trigger Voltage (Continuous dc) ($V_{AK} = 12 \text{ Vdc}$, $R_{L} = 100 \Omega$, $T_{C} = -40 ^{\circ}\text{C}$)		V_{gT}	-	1.0	1.5	V	
Gate Non-Trigger Voltage ($V_{AK} = 12 \text{ Vdc}, R_{I} = 100 \Omega, T_{J} = 125^{\circ}\text{C}$)		V_{gd}	0.2	_	_	V	
		T _C = 25°C		-	18	40	A
		$T_c^c = -40^{\circ}C$	-	-	80	mA	
* Turn-On Time ($I_{TM} = 25 \text{ A}$, $I_{GT} = 50 \text{ mAdc}$)		t _{gt}	-	1.5	2.0	μs	
Turn Off Time (\(\sigma \) = rated voltage)	$(I_{TM} = 25 \text{ A}, I_{R} =$	= 25 A)	t _q	-	15	-	μs
Turn-Off Time (V_{DRM} = rated voltage)	$(I_{TM} = 25 \text{ A}, I_{R} =$	= 25 A, T, = 125 °C)	t _a	-	35	-	μs

^{*}Indicates JEDEC Registered Data
2. Pulse Test: Pulse Width ≤ 300 µsec, Duty Cycle ≤ 2%.



Recommended Operating Conditions may affect device reliability.

1. V_{DBM} and V_{SBM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Dynamic Characteristics

Characteristic	Symbol	Min	Тур	Max	Unit
Critical Rate of Rise of Off-State Voltage (Gate Open, Rated V _{DRM} , Exponential Waveform)	dv/dt	-	50	-	V/µs

Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Forward Off State Voltage
I _{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Reverse Off State Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Maximum On State Voltage
I _H	Holding Current

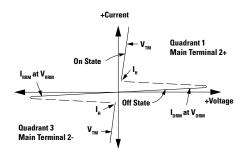


Figure 1. AverageCurrent Derating

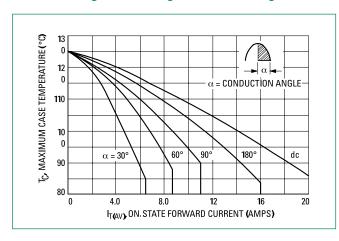


Figure 2. Maximum On-State Power Dissipation

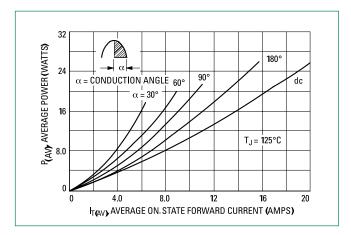


Figure 3. Typical On-State Characteristics

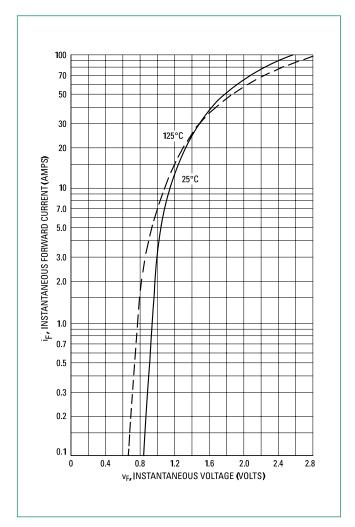


Figure 4. Maximum Non-Repetitive Surge Current

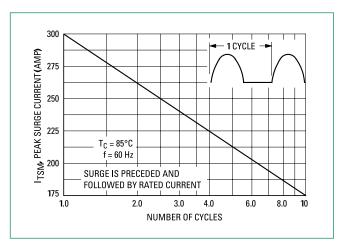
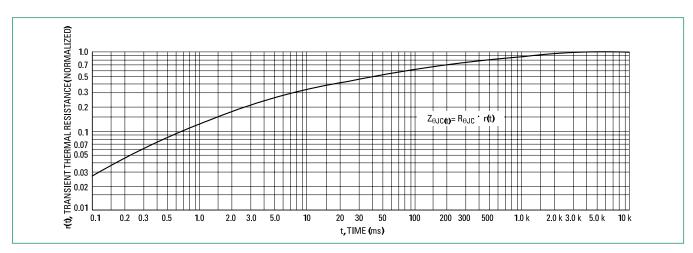


Figure 5. Thermal Response





Typical Trigger Characteristics

Figure 6. Typical Gate Trigger Current vs. Junction Temperature

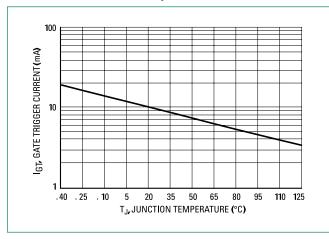


Figure 8. Typical Holding Current vs. Junction Temperature

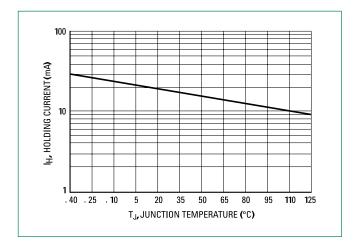


Figure 7. Typical Gate Trigger Voltage vs. Junction Temperature

